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(54) COIL SUBSTRATE, MOTOR COIL SUBSTRATE, AND MOTOR

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(57)ABSTRACT

A coil substrate includes a flexible substrate, and a coil including a first wiring formed on a first surface of the flexible substrate and a second wiring formed on a second surface of the flexible substrate on the opposite side with respect to the first surface of the flexible substrate. The coil is formed such that an inter-wiring distance of the first wiring formed on the first surface of the flexible substrate is larger than an inter-wiring distance of the second wiring formed on the second surface of the flexible substrate.

